



**CHENMKO ENTERPRISE CO.,LTD**

Halogens free devices

**SURFACE MOUNT  
NPN/PNP Silicon AF Transistor Array**

**VOLTAGE 80 Volts CURRENT 0.5 Ampere**

**CHT06UPNGP**

#### APPLICATION

- \* AF input stages and driver applicationon equipment.
- \* Other switching applications.

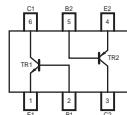
#### FEATURE

- \* Small surface mounting type. (SC-74/SOT-457)
- \* High current gain.
- \* Suitable for high packing density.
- \* Low collector-emitter saturation.
- \* High saturation current capability.
- \* Two internal isolated NPN/PNP transistor in one package.

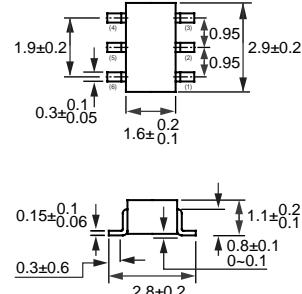
#### CONSTRUCTION

- \* NPN/PNP transistor in one package.

#### CIRCUIT



**SC-74/SOT-457**



Dimensions in millimeters

**SC-74/SOT-457**

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	—	80	V
$V_{CEO}$	collector-emitter voltage	open base	—	80	V
$V_{EBO}$	emitter-base voltage	open collector	—	4	V
$I_C$	collector current (DC)		—	500	mA
$I_{CM}$	peak collector current		—	1000	mA
$I_{BM}$	peak base current		—	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$ ; note 1	—	330	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		—	150	°C
$T_{amb}$	operating ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

## RATING CHARACTERISTIC CURVES ( CHT06UPNGP )

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	note 1	105	K/W

#### Note

- Transistor mounted on an FR4 printed-circuit board.

### CHARACTERISTICS

$T_{amb} = 25^\circ C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = 80\ V$	—	100	nA
		$I_C = 0; V_{CB} = 80\ V; T_A = 150^\circ C$	—	20	uA
$I_{CEO}$	emitter cut-off current	$I_C = 0; V_{CE} = 60\ V$	—	100	nA
$h_{FE}$	DC current gain	$I_C = 10\ mA; V_{CE} = 1.0V; \text{note 1}$	100	—	
		$I_C = 100\ mA; V_{CE} = 1.0V$	100	—	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 100\ mA; I_B = 10\ mA$	—	250	mV
$V_{BE(ON)}$	base-emitter saturation voltage	$I_C = 100\ mA; V_{CE} = 1\ V$	—	1.2	V
$C_c$	collector capacitance	$I_E = i_e = 0; V_{CB} = 10V; f = 1\ MHz$	—	12	pF
$C_e$	emitter capacitance	$I_C = i_e = 0; V_{BE} = 500\ mV; f = 1\ MHz$	—	120	pF
$f_T$	transition frequency	$I_C = 20\ mA; V_{CE} = 5\ V; f = 100\ MHz$	100	—	MHz
$F$	noise figure	$I_C = 100\ \mu A; V_{CE} = 5\ V; R_S = 1\ k\Omega; f = 1.0\ kHz$	—	4	dB

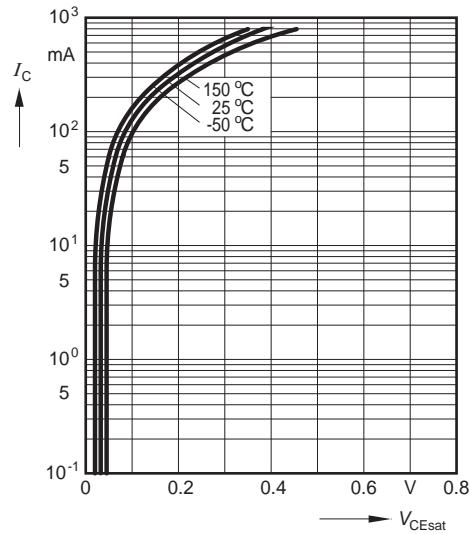
#### Note

- Pulse test:  $t_p \leq 300\ \mu s; \delta \leq 0.02$ .

## RATING CHARACTERISTIC CURVES ( CHT06UPNGP )

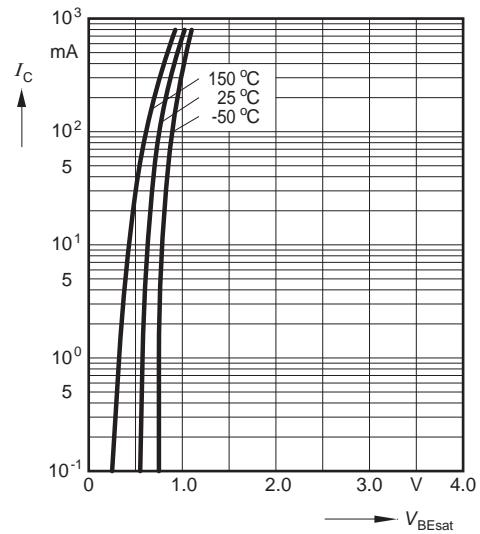
**Collector-emitter saturation voltage**

$$I_C = f(V_{CEsat}), h_{FE} = 10$$



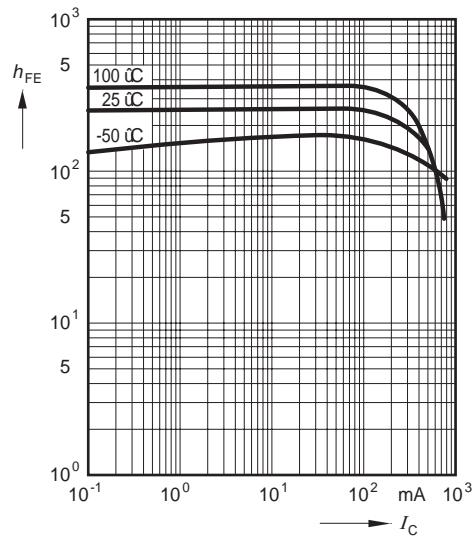
**Base-emitter saturation voltage**

$$I_C = f(V_{BESat}), h_{FE} = 10$$



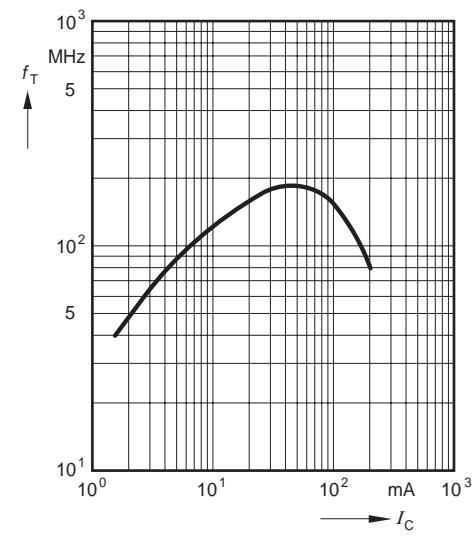
**DC current gain  $h_{FE} = f(I_C)$**

$$V_{CE} = 5V$$



**Transition frequency  $f_T = f(I_C)$**

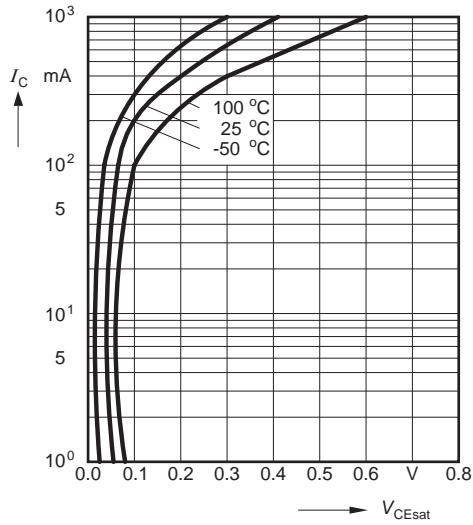
$$V_{CE} = 5V$$



## RATING CHARACTERISTIC CURVES ( CHT06UPNGP )

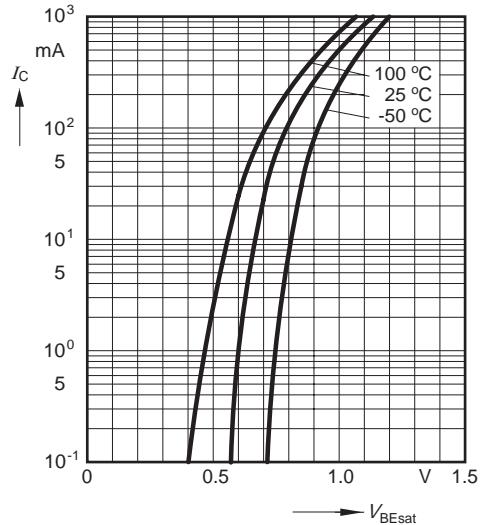
**Collector-emitter saturation voltage**

$$I_C = f(V_{CEsat}), h_{FE} = 10$$



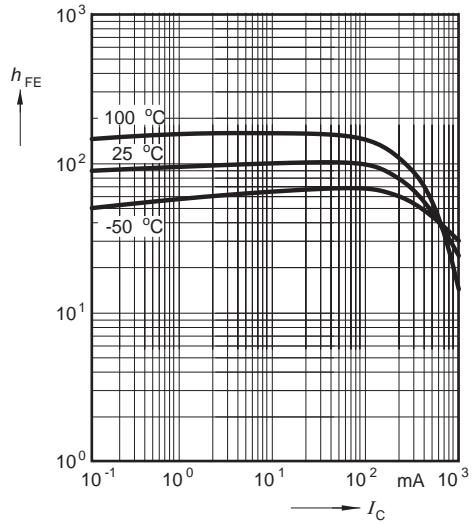
**Base-emitter saturation voltage**

$$I_C = f(V_{BEsat}), h_{FE} = 10$$



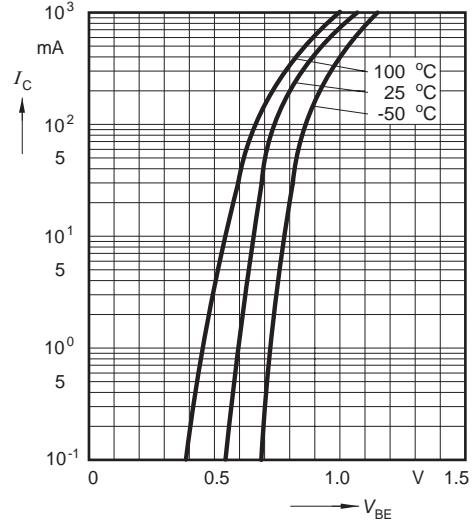
**DC current gain  $h_{FE} = f(I_C)$**

$$V_{CE} = 1\text{V}$$



**Collector current  $I_C = f(V_{BE})$**

$$V_{CE} = 1\text{V}$$



## RATING CHARACTERISTIC CURVES ( CHT06UPNGP )

Transition frequency  $f_T = f(I_C)$

$V_{CE} = 5V$

